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(54) Title: ASSEMBLY HAVING A FACE-TO-FACE BONDED CHIPLET

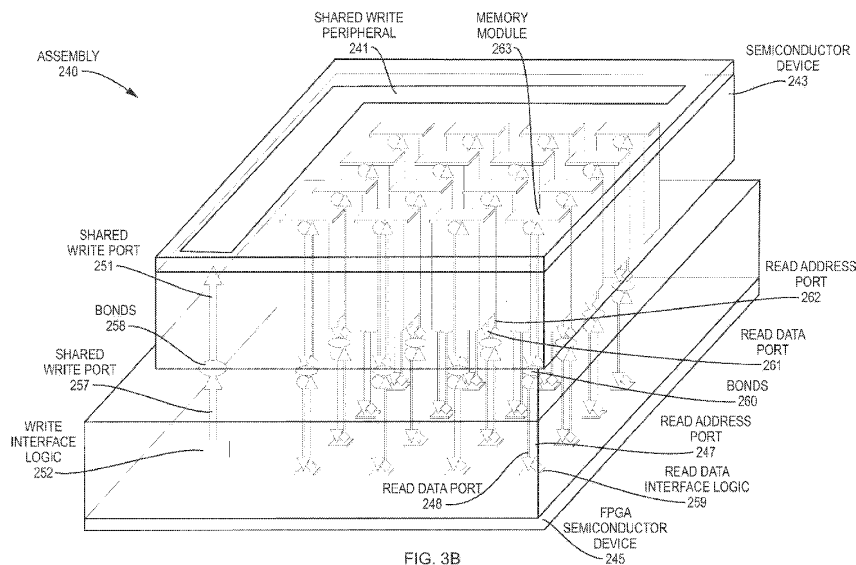


FIG. 3B

(57) Abstract: An integrated circuit (240), and related method, are disclosed. The integrated circuit (240) includes a first semiconductor device (245). The first semiconductor device (245) includes a first programmable gate array (246); a plurality of interface logics (252, 259) including a first interface logic (259); and a first memory port connected to a first set of bonds (258, 260) on a surface of the first semiconductor device (245). The first programmable gate array (245) is operatively coupled to the first interface logic (252) to communicate via the first memory port (251).

[Continued on next page]

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